



Material Content Data Sheet



Sales Product Name		TLE4913		Issued		29. August 2013		
MA#		MA000508952						
Package		PG-SC59-3-4		Weight*		13.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.583	4.22	4.22	42159	42159
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		76	
	non noble metal	titanium	7440-32-6	0.005	0.04		379	
	non noble metal	chromium	7440-47-3	0.016	0.11		1138	
	non noble metal	copper	7440-50-8	5.224	37.78	37.94	377819	379412
wire	noble metal	gold	7440-57-5	0.012	0.09	0.09	858	858
encapsulation	organic material	carbon black	1333-86-4	0.057	0.41		4137	
	plastics	brominated resin	-	0.072	0.52		5171	
	inorganic material	antimonytrioxide	1309-64-4	0.143	1.03		10343	
	plastics	epoxy resin	-	1.301	9.41		94118	
	inorganic material	silicondioxide	60676-86-0	5.577	40.33	51.70	403365	517134
leadfinish	non noble metal	tin	7440-31-5	0.258	1.87	1.87	18667	18667
plating	noble metal	silver	7440-22-4	0.363	2.63	2.63	26281	26281
glue	plastics	epoxy resin	-	0.037	0.27		2711	
	noble metal	silver	7440-22-4	0.177	1.28	1.55	12778	15489
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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